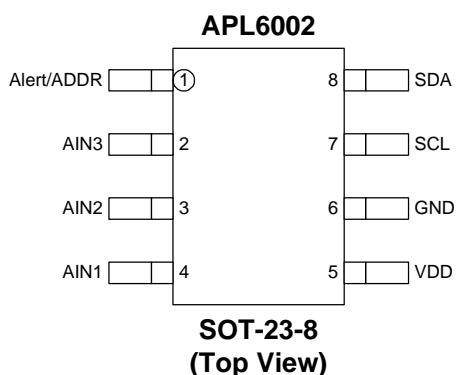


## Low-Power, 8-bit, 3-Channel Analog to Digital Converters

### Features

- Supply Input Voltages Range: 2.8V to 5.5V
- 100 $\mu$ A Low Supply Current
- 3-Ch Analog Voltage Input: AIN1, AIN2, AIN3
- High Accuracy Nonlinearity:  $\pm 1.5$ LSB
- High Accuracy A/D Resolution: 10mV
- High Accuracy A/D Full Scale Range: 1~3.56V
- Built-in Alert Flag Functions
- Built-in I<sup>2</sup>C Address Programming Functions
- I<sup>2</sup>C interface with 8-bit AD converter
- SOT23-8 with Lead Free & RoHS compliant

### Pin Configurations



### General Description

The APL6002 is a precision analog-to-digital converters (ADCs) with 8 bits of resolution, which designed with precision, low power and ease of implementation in mind. Data are transferred via an I<sup>2</sup>C-compatible serial interface. Three voltage sensing inputs are available for monitoring the temperature of the system. It measures voltage from the monitor place to GND by NTC resistor divider voltages. The sensed voltages are digitized and interfaced with microprocessor by I<sup>2</sup>C bus for advanced power management procedures.

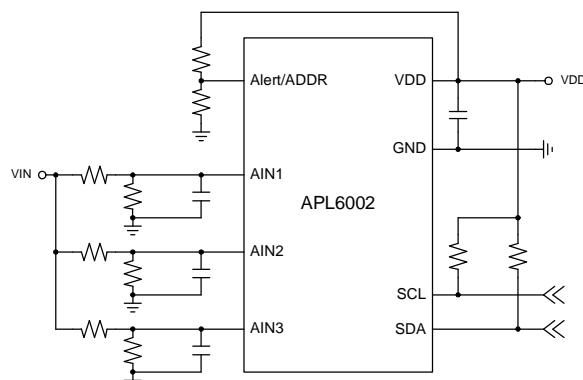
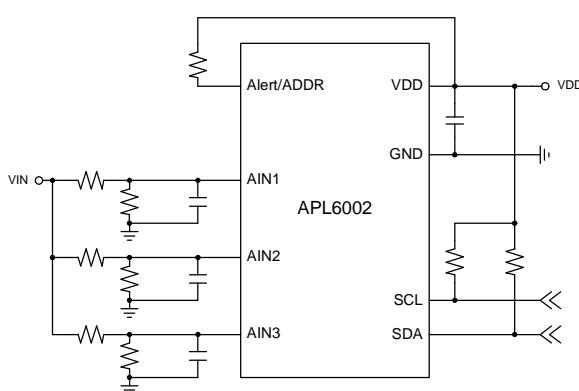
The APL6002 operates from a single power supply ranging from 2.8V to 5.5V.

This APL6002 is available in SOT23-8 package.

### Applications

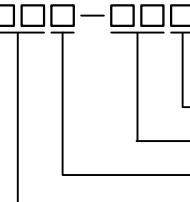
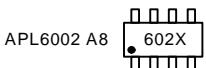
- Phone & NB Application
- Temperature Measurement
- Portable Instrumentation
- Consumer Goods

### Simplified Application Circuit



ANPEC reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

## Ordering and Marking Information

 APL6002 	Assembly Material Handling Code Temperature Range Package Code	Package Code A8 : SOT-23-8 Operating Ambient Temperature Range I : -40 to 85°C Handling Code TR : Tape & Reel Assembly Material G : Halogen and Lead Free Device
	X : Date Code	

Note : ANPEC lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS. ANPEC lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020D for MSL classification at lead-free peak reflow temperature. ANPEC defines "Green" to mean lead-free (RoHS compliant)and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

## Absolute Maximum Ratings (Note 1)

Symbol	Parameter	Rating	Unit
V <sub>D</sub> D	VDD Supply Voltage, VDD to GND	-0.3 ~ 6.0	V
V <sub>I/O</sub>	Input & Output or I/O (Alert/ADDR, SCL, SDA, AIN1, AIN2, AIN3) voltages	-0.3 ~ VDD	V
P <sub>D</sub>	Power Dissipation	Internally Limited	W
T <sub>J</sub>	Junction Temperature	150	°C
T <sub>STG</sub>	Storage Temperature	-65 ~ 150	°C
T <sub>SDR</sub>	Maximum Lead Soldering Temperature(10 Seconds)	260	°C
V <sub>ESD</sub>	Minimum ESD Rating	(Human Body Mode) (MM Mode)	±2 0.2
			kV

Note1: Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## Thermal Characteristics

Symbol	Parameter	Typical Value	Unit
θ <sub>JA</sub>	Junction-to-Ambient Resistance in free air (Note 2)	230	°C/W

Note 2 : θ<sub>JA</sub> is measured with the component mounted on a high effective thermal conductivity test board in free air.

## Recommended Operating Conditions (Note 3)

Symbol	Parameter	Range	Unit
V <sub>D</sub> D	VDD Supply Voltage, VDD to GND	2.8 ~ 5.5	V
V <sub>I/O</sub>	Input & Output pins (Alert/ADDR, SCL, SDA) voltage	0 ~ VDD	V
V <sub>AIN</sub>	Input pins (AIN1, AIN2, AIN3) voltage	1 ~ 3.56	V
T <sub>A</sub>	Ambient Temperature	-40 ~ 85	°C
T <sub>J</sub>	Junction Temperature	-40 ~ 125	°C

## Electrical Characteristics

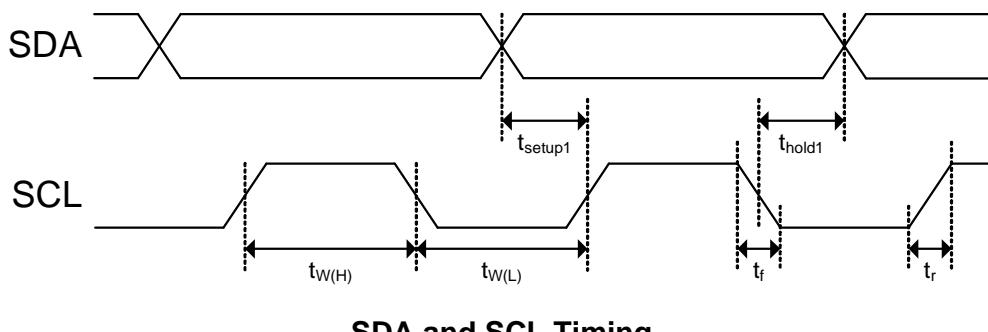
Unless otherwise specified, these specifications apply over  $V_{DD}=5V$ , and  $T_J = -40$  to  $85^{\circ}C$ . Typical values are at  $T_J=25^{\circ}C$ .

<b>Symbol</b>	<b>Parameter</b>	<b>Test condition</b>	<b>Specification</b>			<b>Unit</b>
			<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	
<b>SUPPLY CURRENT</b>						
$I_{VDD}$	VDD Input Current		-	80	100	uA
<b>POWER-ON RESET (POR)</b>						
$V_{POR}$	VDD POR Threshold Voltage	VDD Rising	-	2.35	2.6	V
$V_{POR\_Hys}$	VDD POR Hysteresis Voltage	VDD Falling	-	0.1	-	V
<b>Voltage Monitor</b>						
A/D	A/D Resolution		-	10	-	mV/LSB
	A/D Full Scale Range		1	-	3.56	V
	Differential nonlinearity		-	-	1.5	LSB
	Differential nonlinearity	VDD=3.6V	-	-	2.5	LSB
	Integral nonlinearity		-	-	1.5	LSB
	Integral nonlinearity	VDD=3.6V	-	-	2.5	LSB
	Input Bias Current		-	-	10	nA
	AIN1, AIN2, AIN3 Monitor Time		-	0.6	0.72	ms
<b>Address Setting and Alert Output</b>						
ADDR	Address Latch Time		-	-	10	ms
	Address 1 Voltage Range	Address = 0x7E (Hex)	92	95	100	%VDD
	Address 2 Voltage Range	Address = 0x7C (Hex)	82	85	88	%VDD
	Address 3 Voltage Range	Address = 0x7A (Hex)	72	75	78	%VDD
	Address 4 Voltage Range	Address = 0x78 (Hex)	63	65	68	%VDD
	Address 5 Voltage Range	Address = 0x76 (Hex)	52	55	58	%VDD
	Address 6 Voltage Range	Address = 0x74 (Hex)	42	45	48	%VDD
	Address 7 Voltage Range	Address = 0x72 (Hex)	32	35	38	%VDD
	Address 8 Voltage Range	Address = 0x70 (Hex)	0	25	28	%VDD
Alert	Alert Output Low Voltage	When Alert/ADDR pin pull low, $I_{ALT}=10mA$	-	-	0.2	V
		When Alert/ADDR pin pull low, $I_{ALT}=50mA$	-	-	0.8	V
	Alert Pull Low Pulse Time	When Alert/ADDR pin Alert	-	50	-	us
	Alert Pull Low cycle Time	When Alert/ADDR pin Alert	-	2	-	s
	Alert/ADDR Leakage Current	$V_{Alert/ADDR}=5V$	-	-	100	nA
<b>I<sup>2</sup>C Interface</b>						
$F_{I2C}$	I <sup>2</sup> C Clock Rate Range		-	-	400	kHz
	I <sup>2</sup> C Input High Voltage		1.4	-	-	V
	I <sup>2</sup> C Input Low Voltage		-	-	0.4	V
	I <sup>2</sup> C Leakage Current	$V_{SCL}=V_{SDA}=5V$	-	-	100	nA

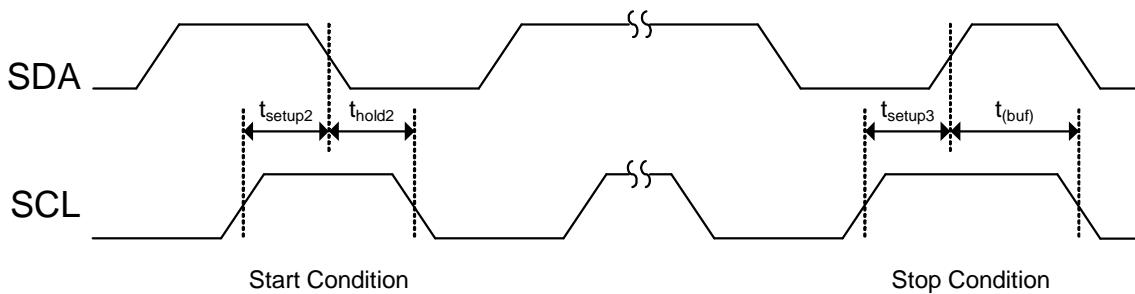
## Electrical Characteristics (Cont.)

Timing characteristics for I<sup>2</sup>C Interface signals over recommended operating conditions (unless otherwise noted)

Symbol	Parameter	Fast Speed		Unit
		Min.	Max.	
f <sub>SCL</sub>	Frequency, SCL	-	400	kHz
t <sub>W(H)</sub>	Pulse Duration, SCL High	600	-	ns
t <sub>W(L)</sub>	Pulse Duration, SCL Low	1300	-	ns
t <sub>r</sub>	Rise Time, SCL and SDA	20+0.1 C <sub>L</sub> (pF)	300	ns
t <sub>f</sub>	Fall Time, SCL and SDA	20+0.1 C <sub>L</sub> (pF)	300	ns
t <sub>setup1</sub>	Setup Time, SCL to SDA	100	-	ns
t <sub>hold1</sub>	Hold Time, SCL to SDA	100	-	ns
t <sub>(buf)</sub>	Bus Free Time Between Stop and Start Condition	1300	-	ns
t <sub>setup2</sub>	Setup Time, SCL to Start Condition	600	-	ns
t <sub>hold2</sub>	Hold Time, Start condition to SCL	600	-	ns
t <sub>setup3</sub>	Setup Time, SCL to Stop Condition	600	-	ns
C <sub>L</sub>	Load Capacitance for Each Bus Line	-	400	pF

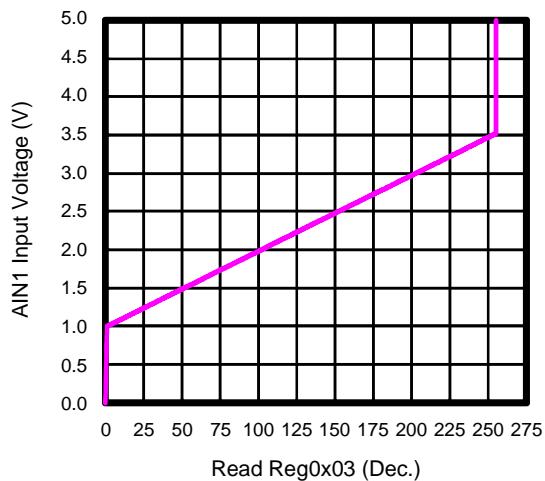
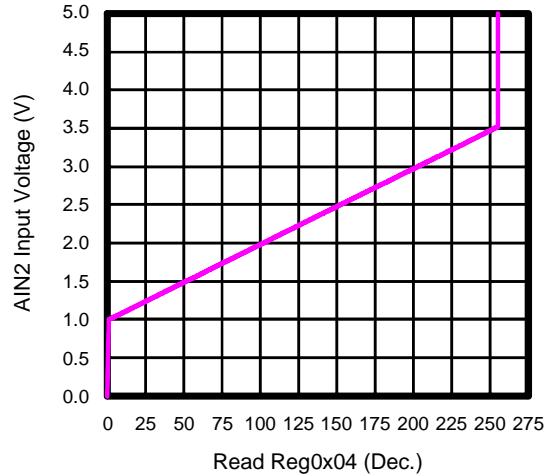
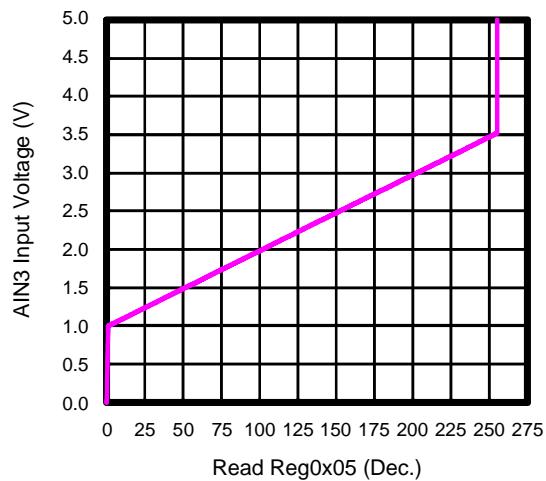
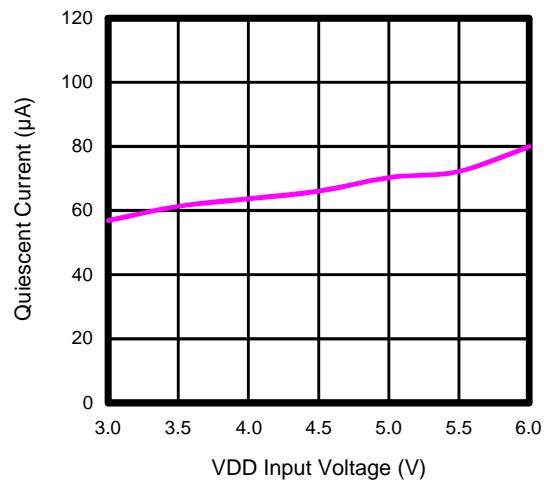
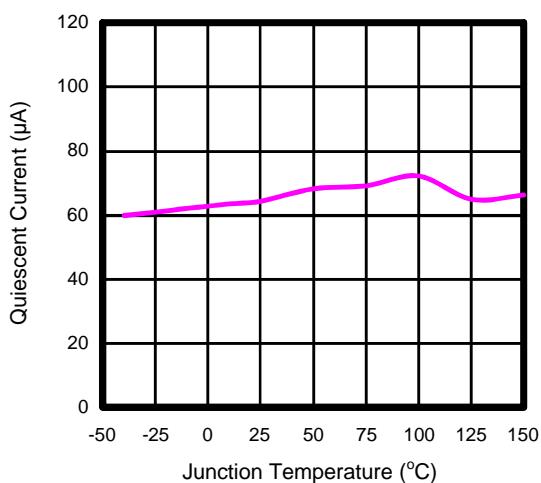
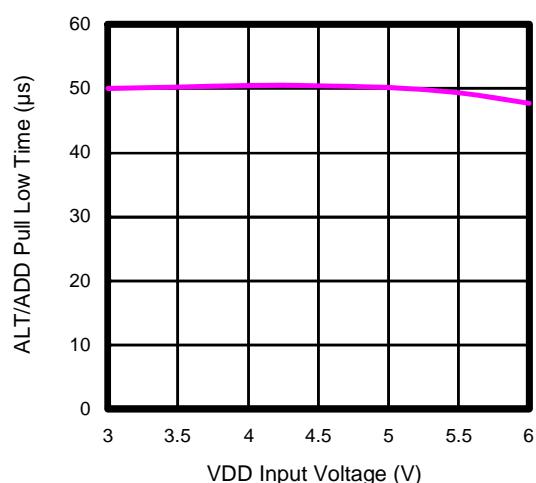


**SDA and SCL Timing**



**Start and Stop Condition Timing**

## Typical Operating Characteristics

**AIN1 vs. Reg0x03****AIN2 vs. Reg0x04****AIN3 vs. Reg0x05****Quiescent Current vs. VDD****Quiescent Current vs. Temperature****Alert Low Pulse Time vs. VDD**

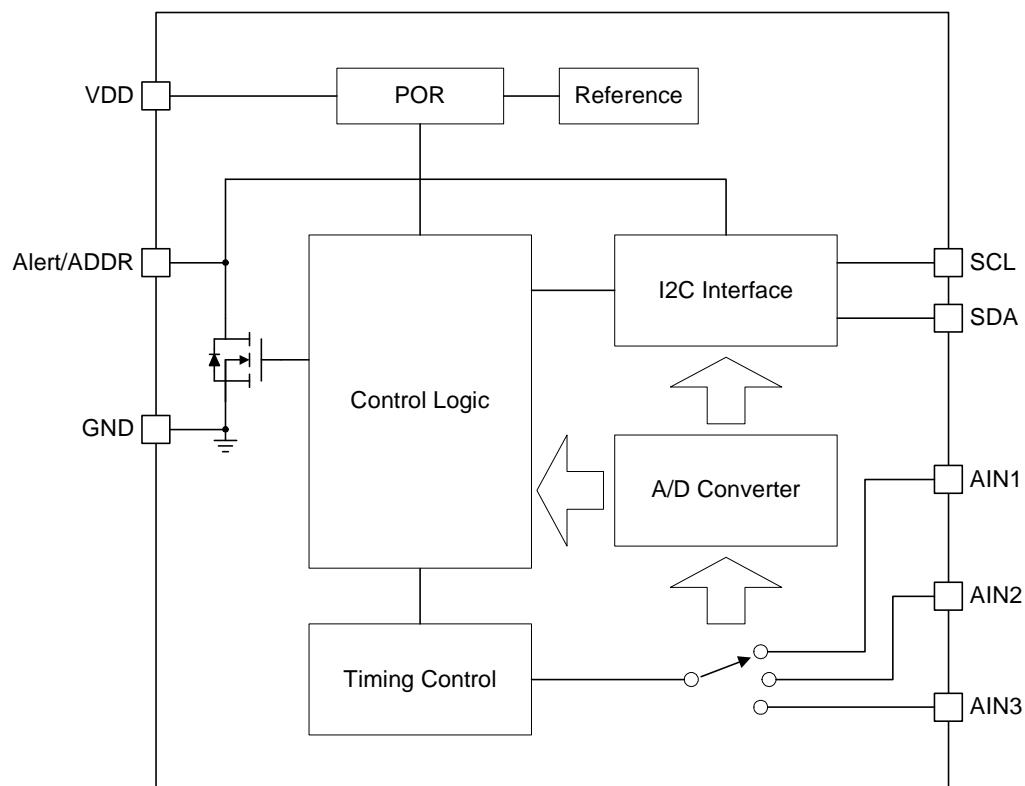
## Typical Operating Characteristics



## Pin Description

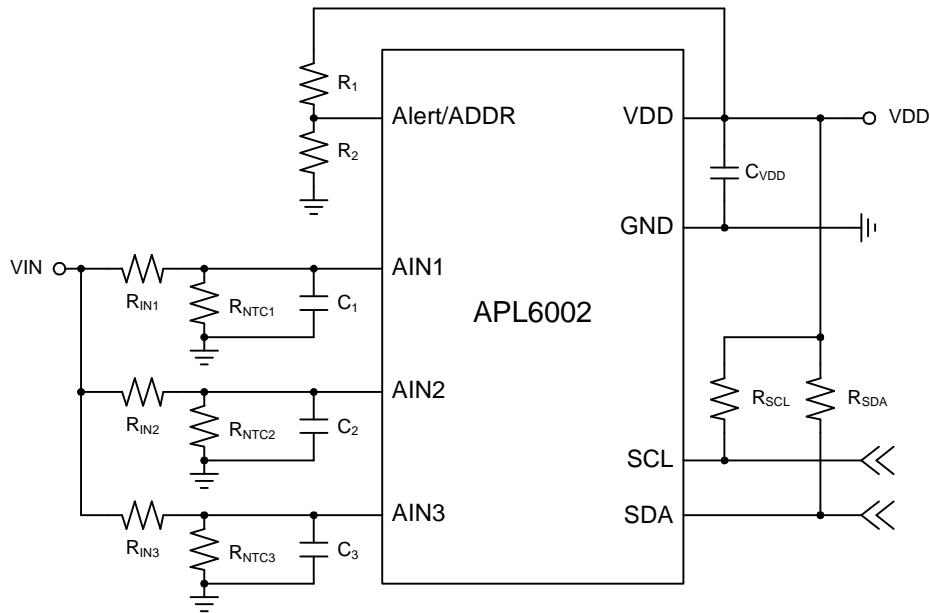
PIN		FUNCTION
NO.	NAME	
1	Alert/ADDR	Address Selection and Thermal Alert. Connect a voltage divider to select the APL6002 I <sup>2</sup> C address. When anyone of V <sub>AINx</sub> is lower than setting voltage, it will pull low and send alert signal to the system. Connect this pin without any capacitor. <b>Do not leave Alert/ADDR pin floating.</b>
2	AIN3	Analog Voltage Input 3.
3	AIN2	Analog Voltage Input 2.
4	AIN1	Analog Voltage Input 1.
5	VDD	Device power supply pin. Connect this pin with 0.1uF capacitor.
6	GND	Signal and Power Ground. All the voltage levels are measured by reference to this pin.
7	SCL	I <sup>2</sup> C interface Clock I/O pin. Connect this pin to I <sup>2</sup> C bus clock signal.
8	SDA	I <sup>2</sup> C interface Data I/O pin. Connect this pin to I <sup>2</sup> C bus data signal.

## Block Diagram

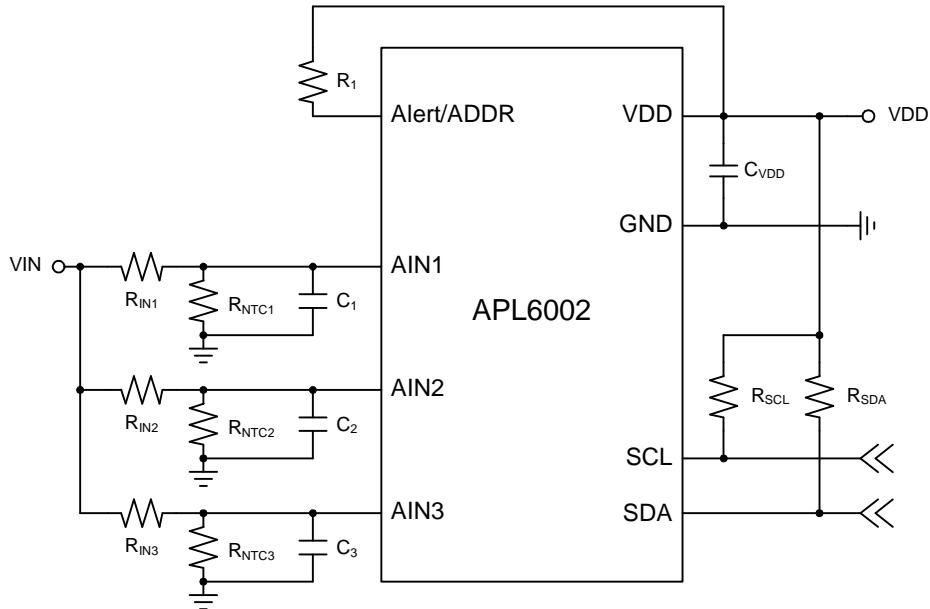


## Typical Application Circuit

The I<sup>2</sup>C Address Programming and Alert Flag functions are used.



The I<sup>2</sup>C Address is used as default and Alert Flag function is unused.



$V_{AINx} = 1\text{--}3.56\text{V}$  is recommended.

$R_{INx}$  and  $R_{NTCx} = 10\text{k}\Omega\text{--}10\text{M}\Omega$  is recommended.

$C_{VDD}, C_1, C_2$  and  $C_3 \geq 0.1\text{\mu F}$  is recommended.

$R_{SCL}$  and  $R_{SDA} = 1\text{k}\Omega\text{--}10\text{k}\Omega$  is recommended.

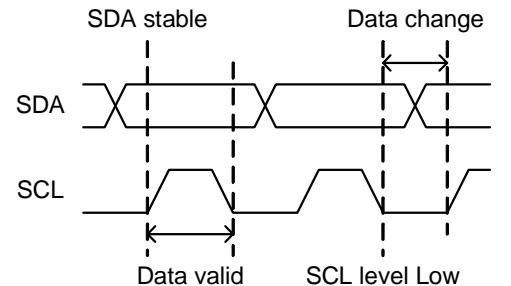
## Function Description

### Input Voltage and Power-On-Reset

The APL6002 can work normally and start monitoring the AINx voltage, when the supply voltage VDD is greater than the POR. The POR threshold is 2.5V typically when the VDD rising.

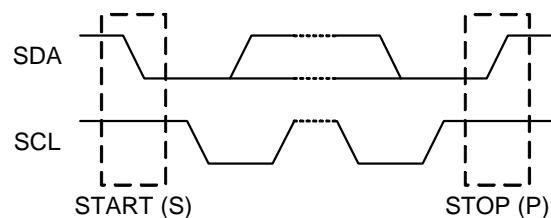
### I<sup>2</sup>C Interface Data Validity

The SCL voltage level can only be changed to Low to High, when the SDA is stable unless the START and STOP status. The SDA can only be changed the voltage level when the SCL voltage is Low.



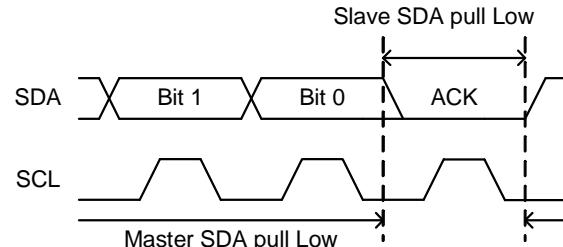
### I<sup>2</sup>C Start and Stop Conditions

The START (S) condition is the SDA transient from High to Low, when SCL is High. The STOP (P) condition is the SDA transient from Low to High, when SCL is High. The STOP condition must send before each START condition.

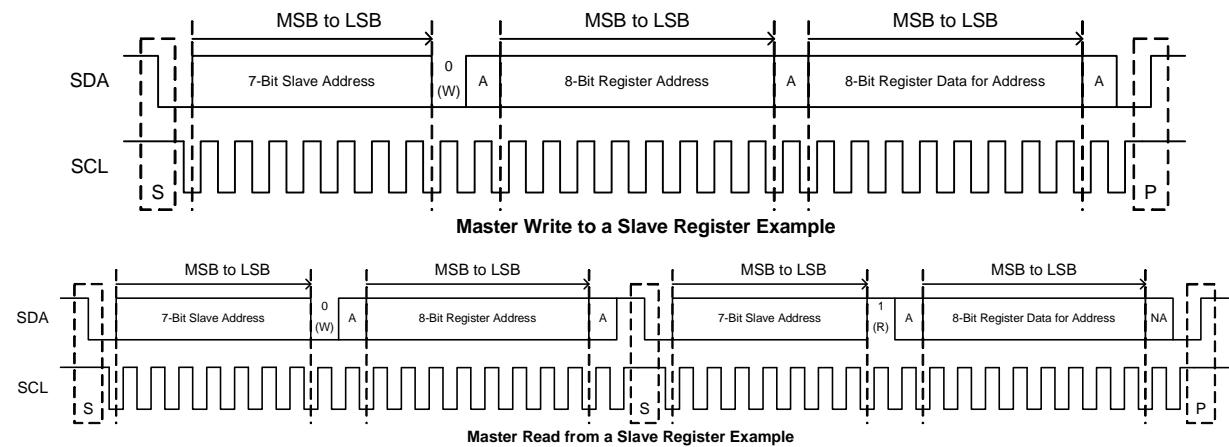


### I<sup>2</sup>C Acknowledge

Each Address and Data are transmitted by using 8 clock pulses with 1 clock pulse Acknowledge (A). The Acknowledge is used for two purposes: one is the device that recognizes its own address. Another one is all of the master and slave to acknowledge receipt the register address or data. The SDA will pull Low to acknowledge.



### Read and Write Protocol



(S=START, P=STOP, A=ACK from Slave, NA=Non-ACK)

## Function Description (Cont.)

### I<sup>2</sup>C Address Programming

The APL6002 I<sup>2</sup>C address is programmable, which can be selected from 0x70h to 0x7Eh by the 7-bit slave address with one R/W bit. The slave device compares the 7-bit slave address with its address and matches. The programmable address is selected by a voltage divider R<sub>1</sub> and R<sub>2</sub>. The Alert/ADDR pin voltage is compared with 8 addresses available internal reference voltage for address programming.

Note: If the address programming function is not used, the Alert/ADDR pin must be connected to VDD via a resistor and the I<sup>2</sup>C address is used as default value 0x7Eh.

### Voltage Monitoring and I<sup>2</sup>C Programming Interface

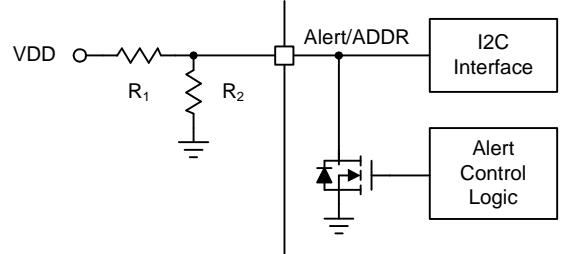
The AINx voltages are digitized directly by high precision A/D converter and interfaced to the I<sup>2</sup>C bus. The AINx voltages are sensed alternately and take 0.6ms every channel.

When the VDD supply voltage range from 2.8 to 5.5V, the A/D converter have 10mV of resolution, and 1 to 3.56V of full scale range. The A/D converter sensing results are stored in the internal register that shows as follow:

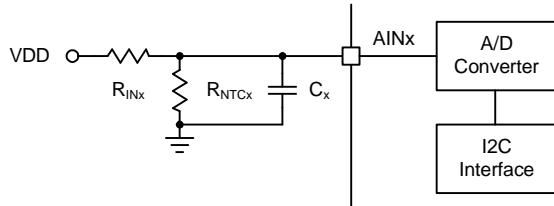
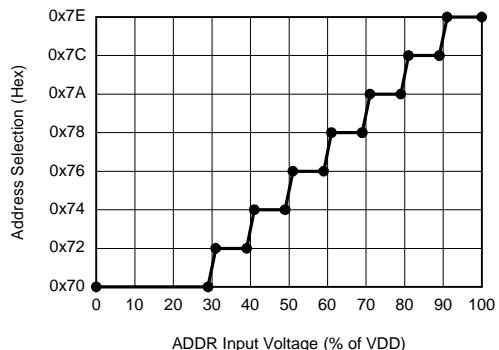
AIN1 A/D data store (TD1): Reg0x03[7] (MSB) ~ Reg0x03[0] (LSB)

AIN2 A/D data store (TD2): Reg0x04[7] (MSB) ~ Reg0x04[0] (LSB)

AIN3 A/D data store (TD3): Reg0x05[7] (MSB) ~ Reg0x05[0] (LSB)



Address	0x70	0x72	0x74	0x76	0x78	0x7A	0x7C	0x7E
R1 (kOhm)	6	5.1	4.3	3.9	3.6	2	1.5	10
R2 (kOhm)	2	2.7	3.6	4.7	6.8	6.2	8.2	Open
ALT/ADDR (% of VDD)	25	35	45	55	65	75	85	100



If the internal register code is read as Code<sub>x</sub> in integer decimal format, the AINx voltage transition to the internal register Reg0x03, Reg0x04 and Reg0x05 calculation as follows:

$$\text{Code}_x = \frac{V_{\text{AIN}x} - 1V}{10mV} \quad \text{or} \quad V_{\text{AIN}x} = (10mV \times \text{Code}_x) + 1V$$

The voltage divider at VIN-R<sub>INx</sub>-R<sub>NTCx</sub>-GND sets the voltage AINx is calculated as:

$$V_{\text{AIN}x} = \text{VIN} \times \frac{R_{\text{NTCx}}}{R_{\text{IN}x} + R_{\text{NTCx}}}$$

According to the above equation:

$$\text{Code}_x = \frac{\left( \text{VIN} \times \frac{R_{\text{NTCx}}}{R_{\text{IN}x} + R_{\text{NTCx}}} \right) - 1V}{10mV}$$

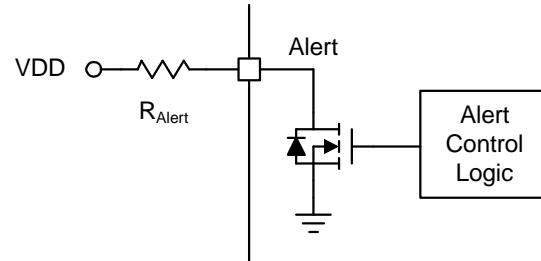
Note: If the AINx pin is not used, that must be pulled to the high level. And the C<sub>x</sub> is recommended to bypass the AINx pin.

## Function Description (Cont.)

### Alert Flag

The Alert Flag is used to indicate the system state.

When the setting condition is established at the AINx voltage, the APL6002 will make the internal MOS in the Alert pin turns on and pull low 50us every 2s cycle time.



### Alert Threshold Level Setting

The Alert levels are set in the internal register by I<sup>2</sup>C interface shows as follows:

AIN1 Alert level set-up (TL1): Reg0x00[7] (MSB) ~ Reg0x00[0] (LSB)

AIN2 Alert level set-up (TL2): Reg0x01[7] (MSB) ~ Reg0x01[0] (LSB)

AIN3 Alert level set-up (TL3): Reg0x02[7] (MSB) ~ Reg0x02[0] (LSB)

If one of conditions is established include  $TL1 \geq TD1$ ,  $TL2 \geq TD2$  or  $TL3 \geq TD3$ , the Alert function will be enabled, and the Alert Indication of internal resistor Reg0x06[6:4] will be set to 1 that shows as below:

If the  $Reg0x00 \geq Reg0x03$  ( $TD1$ ), than the bit  $Reg0x06[4] = 1$ , else the bit  $Reg0x06[4] = 0$

If the  $Reg0x01 \geq Reg0x04$  ( $TD2$ ), than the bit  $Reg0x06[5] = 1$ , else the bit  $Reg0x06[5] = 0$

If the  $Reg0x02 \geq Reg0x05$  ( $TD3$ ), than the bit  $Reg0x06[6] = 1$ , else the bit  $Reg0x06[6] = 0$

**Chip ID: Reg0xB2[7:0] = 0x1A**

### I<sup>2</sup>C Registers Summary

Register Address	Register Name	Bits								Read/Write	Default Value
		D7	D6	D5	D4	D3	D2	D1	D0		
0x00	TL1	TL1[7:0]								R/W	00h
0x01	TL2	TL2[7:0]								R/W	00h
0x02	TL3	TL3[7:0]								R/W	00h
0x03	TD1	TD1[7:0]								R	00h
0x04	TD2	TD2[7:0]								R	00h
0x05	TD3	TD3[7:0]								R	00h
0x06	ALT	Reversed	AM3	AM2	AM1	Reversed				R	00h
0xB2	Chip ID	Chip ID = 0x1A								R	1Ah

## Manufacture Information

APL6002 manufacturing information. Including wafer fab and assembly location.

ANPEC Device	Manufacture	Assembly
APL6002	TSMC	GTK / CJE

ANPEC Electronic Corp.

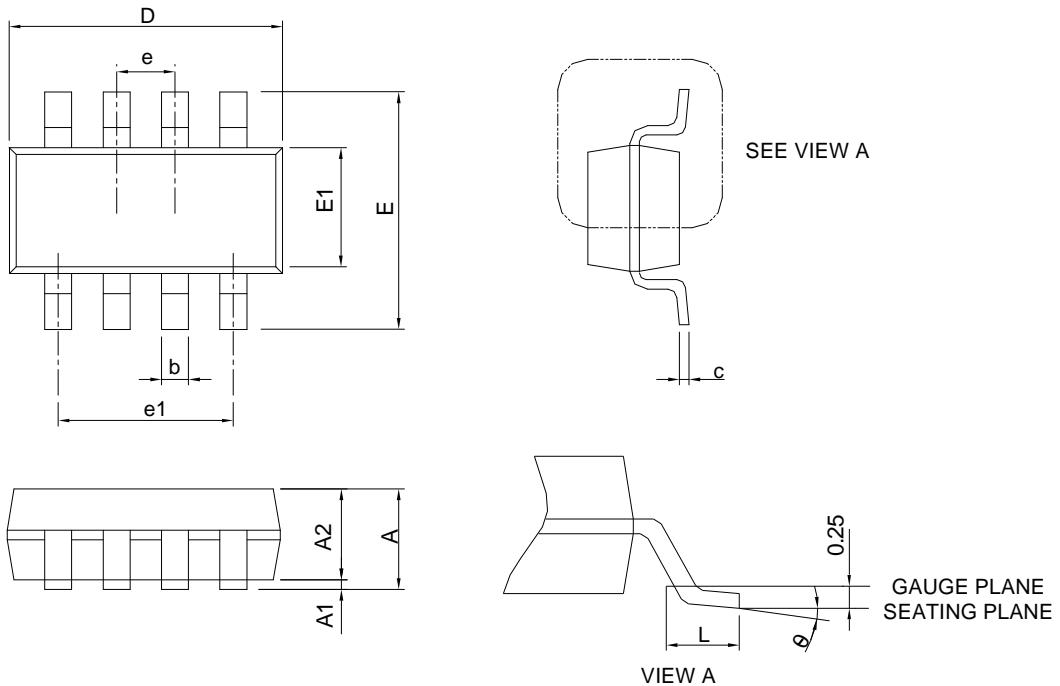
Account manager

Kevin Chang



## Package Information

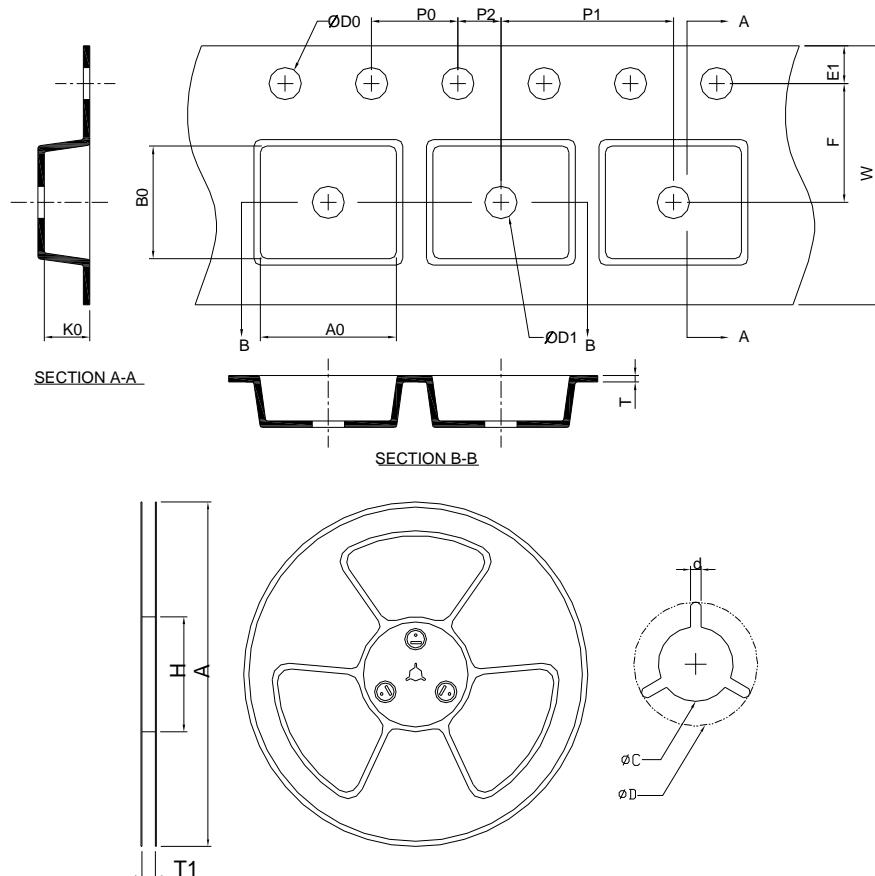
SOT-23-8



SYMBOL	SOT-23-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A		1.45		0.057
A1	0.00	0.15	0.000	0.006
A2	0.90	1.30	0.035	0.051
b	0.22	0.38	0.009	0.015
c	0.08	0.22	0.003	0.009
D	2.70	3.10	0.106	0.122
E	2.60	3.00	0.102	0.118
E1	1.40	1.80	0.055	0.071
e	0.65 BSC		0.026 BSC	
e1	1.95 BSC		0.077 BSC	
L	0.30	0.60	0.012	0.024
θ	0°	8°	0°	8°

- Note : 1. Follow JEDEC MO-178 BA.  
 2. Dimension D and E1 do not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 10 mil per side.

## Carrier Tape & Reel Dimensions



Application	A	H	T1	C	d	D	W	E1	F
SOT-23-8	178.0 ± 2.00	50 MIN.	8.4 + 2.00 - 0.00	13.0 + 0.50 - 0.20	1.5 MIN.	20.2 MIN.	8.0 ± 0.30	1.75 ± 0.10	3.5 ± 0.05
	P0	P1	P2	D0	D1	T	A0	B0	K0
	4.0 ± 0.10	4.0 ± 0.10	2.0 ± 0.05	1.5 + 0.10 - 0.00	1.0 MIN.	0.6 + 0.00 - 0.40	3.20 ± 0.20	3.10 ± 0.20	1.50 ± 0.20

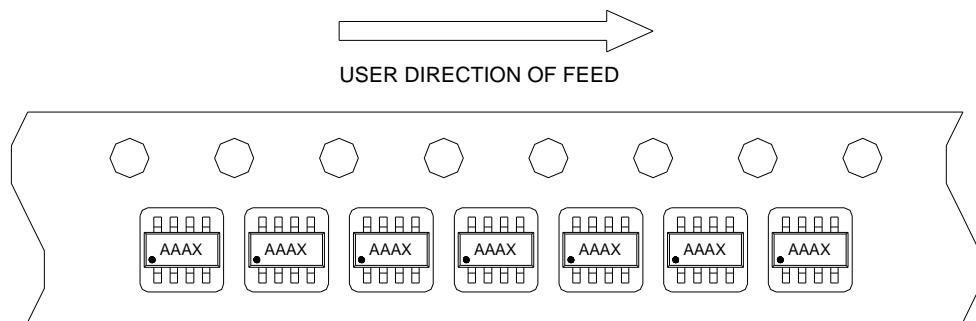
(mm)

## Devices Per Unit

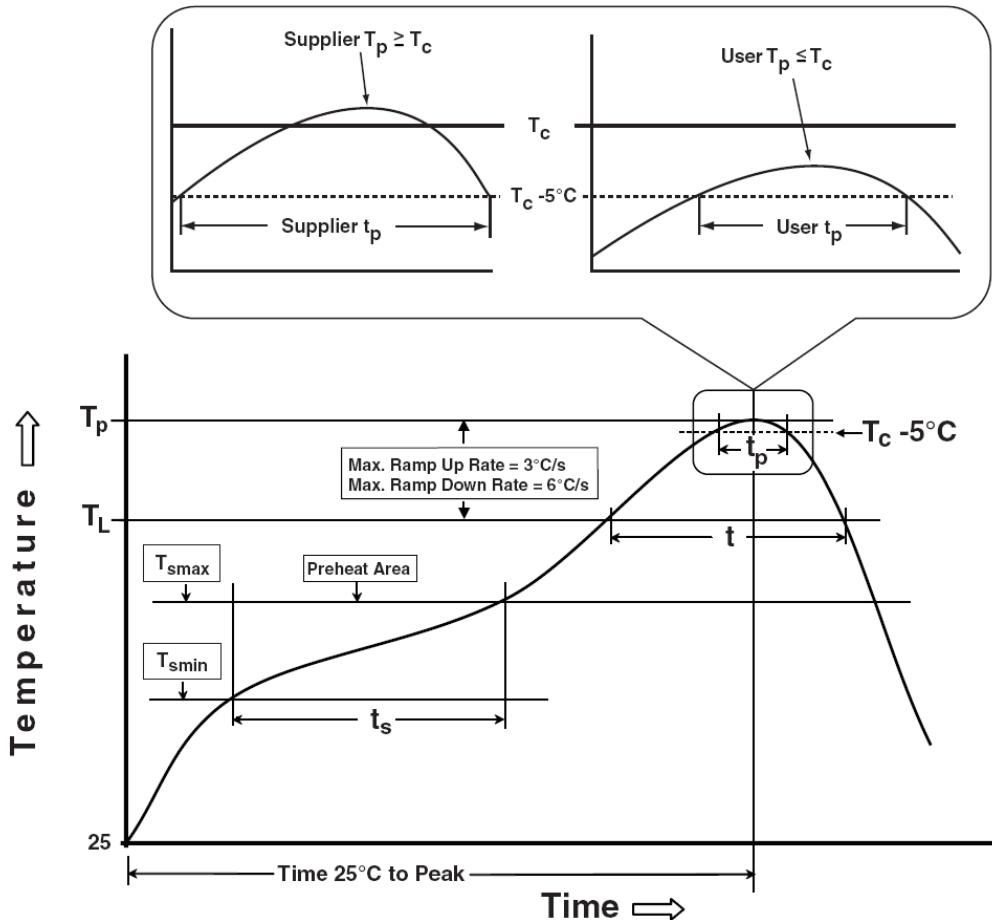
Package Type	Unit	Quantity
SOT-23-8	Tape & Reel	3000

## Taping Direction Information

SOT-23-8



## Classification Profile



## Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
<b>Preheat &amp; Soak</b>		
Temperature min ( $T_{smin}$ )	100 °C	150 °C
Temperature max ( $T_{smax}$ )	150 °C	200 °C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max.	3 °C/second max.
Liquidous temperature ( $T_L$ )	183 °C	217 °C
Time at liquidous ( $t_L$ )	60-150 seconds	60-150 seconds
Peak package body Temperature ( $T_p$ )*	See Classification Temp in table 1	See Classification Temp in table 2
Time ( $t_p$ )** within 5°C of the specified classification temperature ( $T_c$ )	20** seconds	30** seconds
Average ramp-down rate ( $T_p$ to $T_{smax}$ )	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.

\* Tolerance for peak profile Temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.  
\*\* Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.

## Classification Reflow Profiles (Cont.)

Table 1. SnPb Eutectic Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

## Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HOLT	JESD-22, A108	1000 Hrs, Bias @ Tj=125°C
PCT	JESD-22, A102	168 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -65°C~150°C
HBM	MIL-STD-883-3015.7	VHBM≥2KV
MM	JESD-22, A115	VMM≥200V
Latch-Up	JESD 78	10ms, 1 <sub>tr</sub> ≥100mA

## Customer Service

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